

PROCESSING METHOD FOR WAFER

ABSTRACT OF THE DISCLOSURE

A processing method for a wafer includes a thermocompression-bonding sheet arrangement step of arranging, on a front side of the wafer, a thermocompression-bonding sheet of a size sufficient to cover the wafer, an integration step of pressing the thermocompression-bonding sheet under heat by a planarizing member, so that the thermocompression-bonding sheet is planarized and the thermocompression-bonding sheet and the wafer are integrated together, a grinding step of holding the wafer on a side of the thermocompression-bonding sheet on a chuck table of a grinding apparatus and grinding the wafer to a desired thickness while supplying grinding water to a back side of the wafer, and a thermocompression-bonding sheet rinsing step of unloading the integrated wafer from the chuck table and rinsing the thermocompression-bonding sheet.

[Fig. 4]